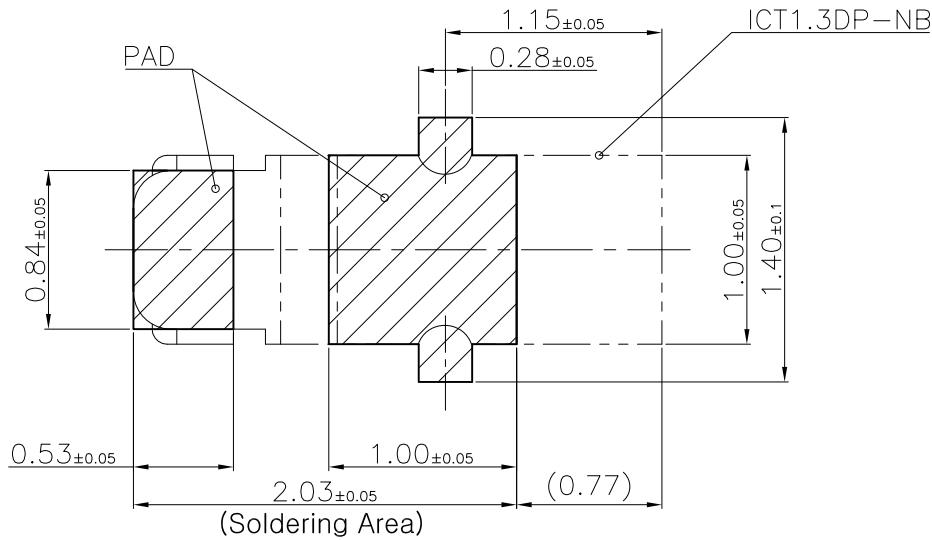
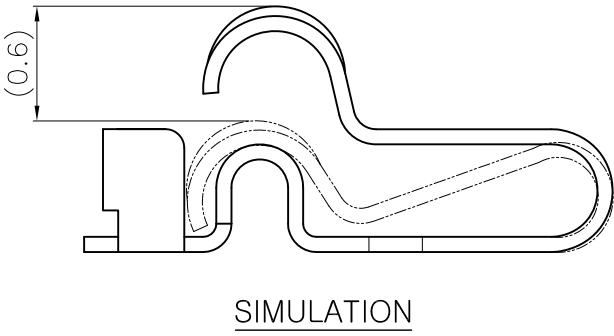
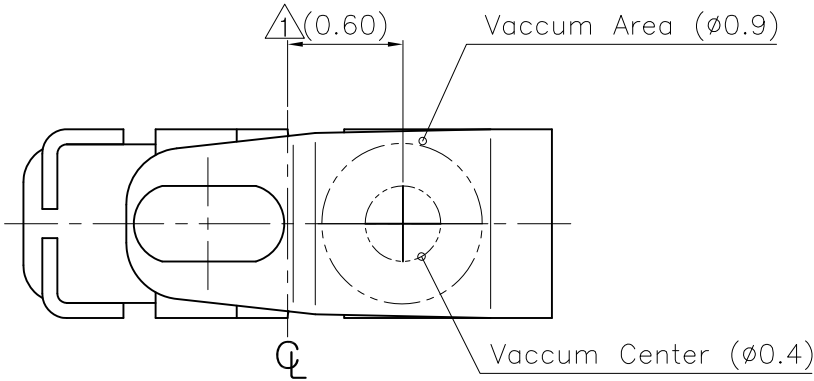
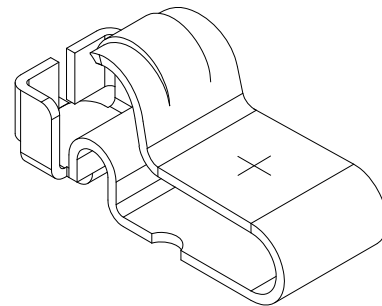
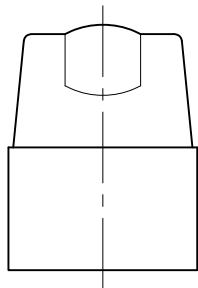
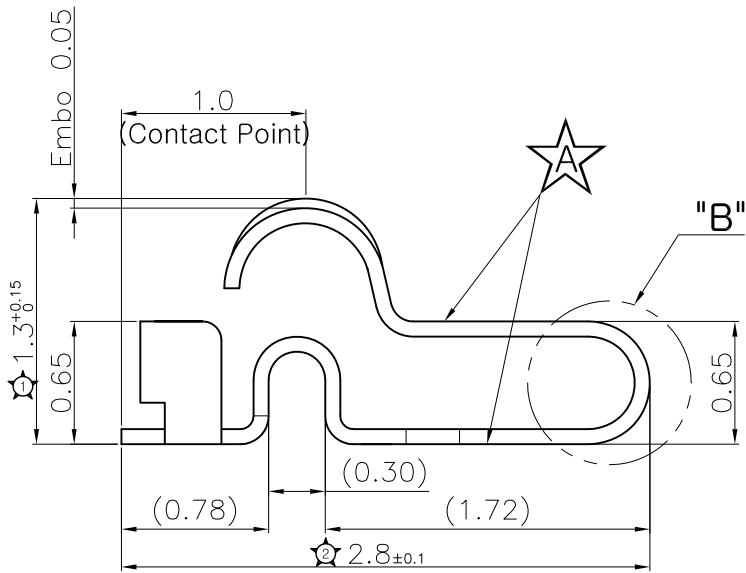


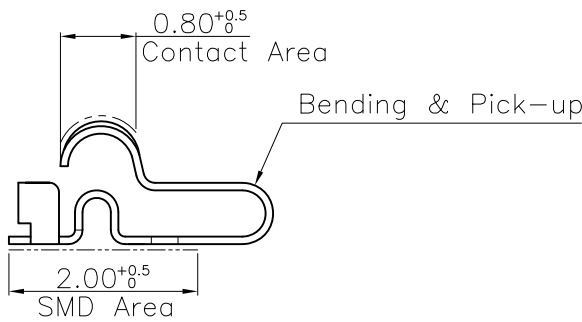
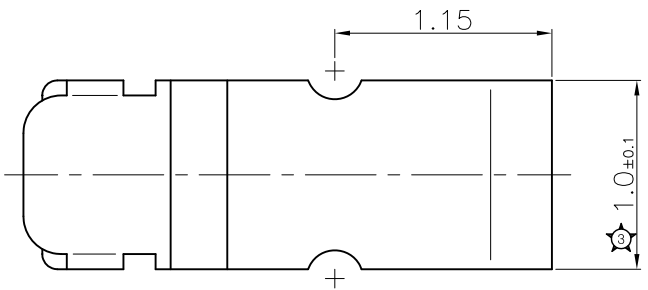
Rev No.	Description of Revision	Date	Name	Reviewed	Approved	ECN No.
△ X 1	각인추가 (고객요청)	2013.10.21	J.H.Cho	Y.J.Park	S.K.Hong	



RECOMMNEDED PCB LAYOUT(Top View)



- *NOTE
1. PLATING
 - Contact Area : Au $0.1 \mu\text{m}$ Min over Ni $1.5 \sim 4.0 \mu\text{m}$.
 - SMD Area : Au $0.05 \mu\text{m}$ Min over Ni $1.50 \sim 4.0 \mu\text{m}$.
 - Bending & Pick-up : Ni $1.5 \sim 3.5 \mu\text{m}$.
 2. ☆: C.T.Q
 3. ☆: 평탄도 0.05 Max.
 4. Contact 가동거리 : 0.6mm
 권장 Contact 높이 : 가동거리의 $60 \sim 80\%$ 범위 내
 ($0.36 \sim 0.48\text{mm}$) => ($0.82 \sim 0.94\text{mm}$)
 * CONTACT 가동거리(Max)는 0.6mm 이상으로 한다.
 5. 제품의 안정적 Contact을 위하여 Bending部 "B" 주위에 기구적인 간섭이 없을 것.
 6. 일반 공차 ± 0.1 적용 할 것.



PLATING AREA (SC=2/1)

1	Contact	Ti-Cu			Note.1		t0.08		
No	Descriptions	Material			Finish		Remarks		
General Tolerance		Scale	N/S	Units	mm	Sheet	HJ-ICT-1.3DP-NB ANTENNA CONTACT		
Dimension	mm (°)	Date	2013. 03. 29.		1 of 1				
X	± 0.2	Drawn	Design	Checked	Reviewed	Approved	TITLE		
X.X	± 0.1								
X.XX	± 0.05	J.H. Cho 2013/04/11		J.S. Kim 2013/04/11	S.C. Choi 2013/04/11	Y.J. Park 2013/04/11	Customer Drawing		
X.XXX	± 0.01								
ANGLE	± 1°	 HYUPJIN CONNECTOR					SW No.		Rev.
							DWG No.	HJ-ICT-1.3DP-NB-A1	1

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